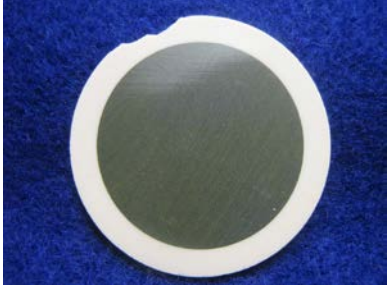
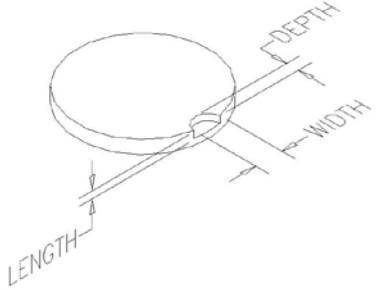

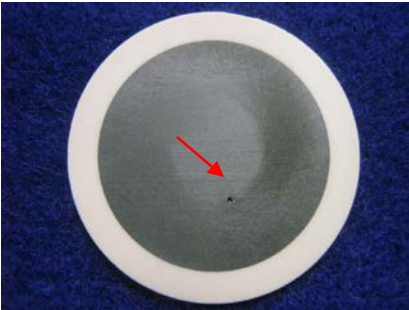


## Inspection Method Sheet

**Part Number:** Generic  
**Drawing Number:** Generic  
**Page** 1 of 5  
**Doc. #:** TT-PC-0436 Rev. 12

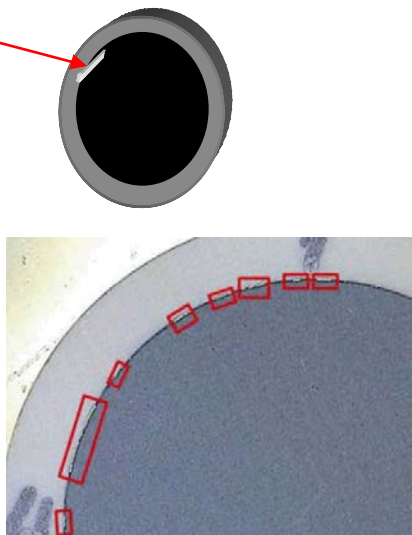
**Part Name:** Assemblies  
**Operation:** Final Inspection  
**Written By:** Anna Huse  
**Date:** 5/1/01

**Applicable customer specifications take precedence over this procedure (reference customer drawing).**

Description / Dimensions	Picture / Detail	Sample Size / Method / Standard
<p><b>1) Inspection for Chips</b> (Material broken off an edge or a corner):</p> <p>No more than 3 chips per part. Any chip under .020" is not recognized. The depth of the chip cannot exceed ½ of the parts thickness.</p> <p><b>Part Size – 1.00" and under</b> No single edge chip <math>\geq</math> .075" in length and width.</p> <p><b>Part Size – Over 1.00"</b> No single edge chip <math>\geq</math> .100" in length and width.</p>	 	<p><b>Method:</b> Visual using a 4X illuminated magnification or greater.</p> <p><b>Sample Size:</b> Refer to appropriate flow chart in TT-PC-0186 for inspection level.</p>
<p><b>2) Inspection for Holes</b> (A pit on the surface of the part):</p> <p>No more than 2 holes per part</p> <p><b>Part Size – 1.00" and under</b> No hole to exceed .030".</p> <p><b>Part Size – Over 1.00"</b> No hole to exceed .040"</p>	 	<p><b>Method:</b> Visual using a 4X illuminated magnification or greater.</p> <p><b>Sample Size:</b> Refer to appropriate flow chart in TT-PC-0186 for inspection level.</p>

**3) Inspection for Air-gaps and Glue-gaps (A gap between the assembly):**

Air gaps are acceptable if they do not exceed 40% of the ferrite circumference.



**Method:** Visual using a 4X illuminated magnification or greater.

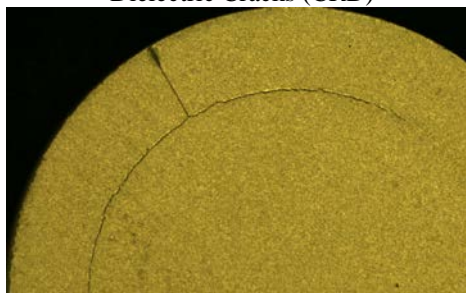
**Sample Size:** Refer to appropriate flow chart in TT-PC-0186 for inspection level.

**4) Inspection for Cracks and Laminations:**

None allowed



Dielectric Cracks (CRD)



**Method:** Visual using a 4X illuminated magnification or greater.

**Sample Size:** Refer to appropriate flow chart in TT-PC-0186 for inspection level.

**5) Inspection for Material Imperfections** (Kiln Reaction, Large Grains, Contamination):

None allowed

**Not Acceptable**

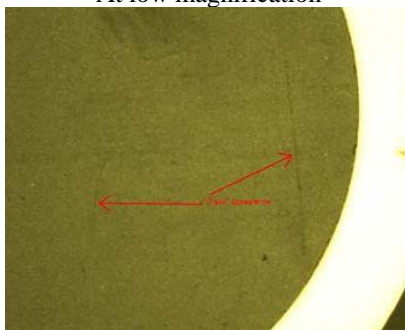


**Method:** Visual using a 4X illuminated magnification or greater.

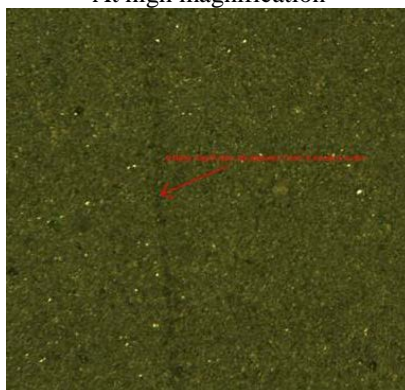
**Sample Size:** Refer to appropriate flow chart in TT-PC-0186 for inspection level.

**Minor scratches are Acceptable**

At low magnification



At high magnification



**6) Inspection for Blemishes** (A discoloration in the material):

No more than 3 blemishes per part

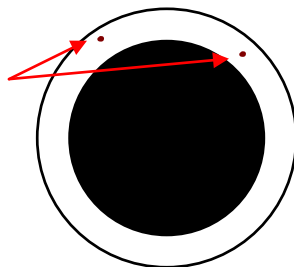
**Part Size – 1.00” and under**

No blemish to exceed .030”.

**Part Size – Over 1.00”**

No blemish to exceed .040”

No blemishes allow if they create a hole.



**Method:** Visual using a 4X illuminated magnification or greater.

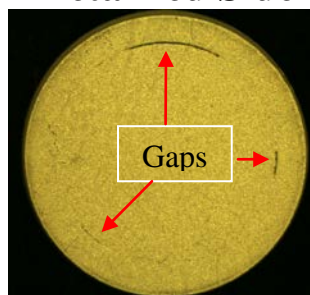
**Sample Size:** Refer to appropriate flow chart in TT-PC-0186 for inspection level.

**7) Inspection for Gaps:**

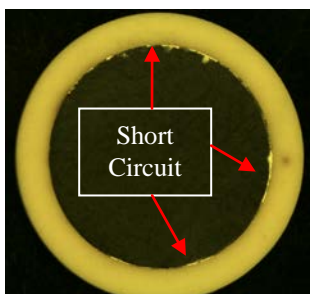
**Gaps:** are acceptable as long as there is no “ Short Circuit” (see *NonMetallized Side* ). When Gaps are detected, Visual Inspection shall be performed on the non-metalized side for any silver spots or trace through the Gap that create “Short Circuit”.

**Short Circuit:** Silver spots or trace on the non-metlized side at the interface area of the Dielectric Ring and Magnetic Disk.

**Metalized Side**



**Non Metalized Side**



**Method:** Visual using a 4X illuminated magnification or greater.

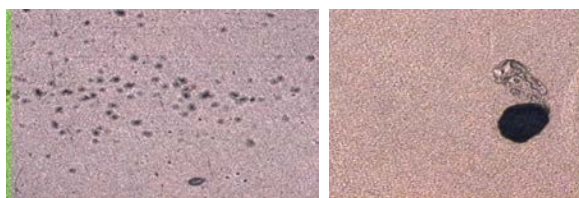
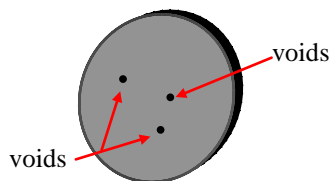
**Sample Size:** Refer to appropriate flow chart in TT-PC-0186 for inspection level.

**8) Inspection for Voids (a hole) and Divots (a dent) in the metallization surface.**

**For Voids:**

No voids  $\geq .040$ ”

No more than 5 voids per part.



**Method:** Visual using a 4X illuminated magnification or greater.

**Sample Size:** Refer to appropriate flow chart in TT-PC-0186 for inspection level.

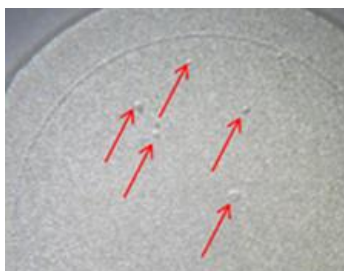
**Continue from section 8:**

**For Divots:**

No divot  $\geq .100$ ”


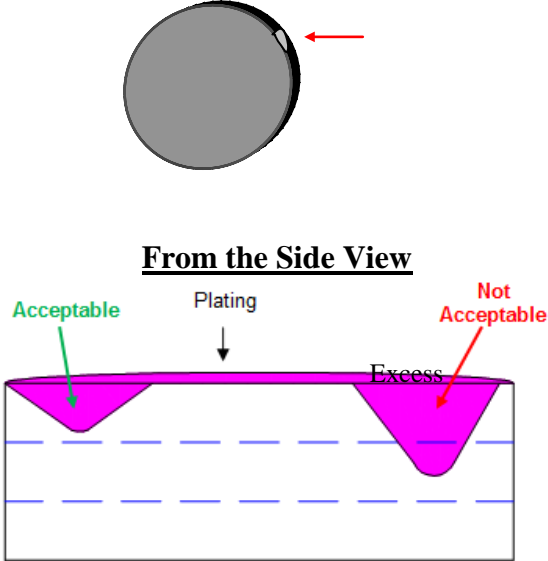
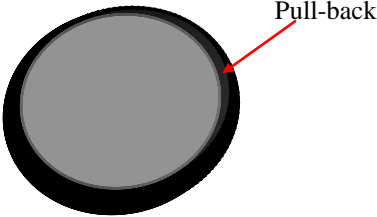
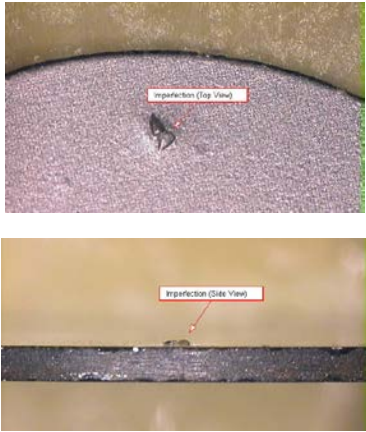
No more than 5 divots per part.

**Note:** No more than 5 of each defect allowed per part



**Method:** Visual using a 4X illuminated magnification or greater.

**Sample Size:** Refer to appropriate flow chart in TT-PC-0186 for inspection level.

<p><b>9) Inspection for Excess metal on non-metalized surface:</b></p> <p>No metal &gt; 0.025" in greatest dimension allowed.</p>		<p><b>Method:</b> Visual using a 4X illuminated magnification or greater.</p> <p><b>Sample Size:</b> Refer to appropriate flow chart in TT-PC-0186 for inspection level.</p>
<p><b>10) Inspection of excess metal on the O.D./edge:</b></p> <ol style="list-style-type: none"> <li>No bridging allowed between top and bottom surfaces</li> <li>Parts are allowed to have excess metal on 1/3 of the thickness.</li> <li>Metal specks not allowed below 2/3 of the part thickness as measure from the metalized side.</li> </ol>		<p><b>Method:</b> Visual using a 4X illuminated magnification or greater.</p> <p><b>Sample Size:</b> Refer to appropriate flow chart in TT-PC-0186 for inspection level.</p>
<p><b>11) Inspection for Pull-back</b> (the ceramic gap between the edge of the part and where the metal begins on the metalized surface):</p> <p><b>All Part Sizes</b> The pull back can not be &gt;0.015"</p>		<p><b>Method:</b> Visual using a 4X illuminated magnification or greater.</p> <p><b>Sample Size:</b> Refer to appropriate flow chart in TT-PC-0186 for inspection level.</p>
<p><b>12) Inspection for visual imperfections on the metallized surface:</b></p> <ul style="list-style-type: none"> <li>No surface imperfections, blisters, debris, excess metal etc. &gt; 0.040" in greatest dimension</li> <li>No discernable surface condition that alters the surface uniformity by producing visible peaks and build-up</li> </ul>		<p><b>Method:</b> Visual using a 4X illuminated magnification or greater.</p> <p><b>Sample Size:</b> Refer to appropriate flow chart in TT-PC-0186 for inspection level.</p>